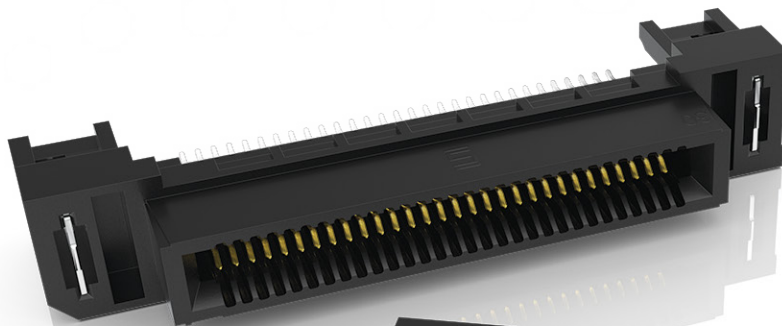


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

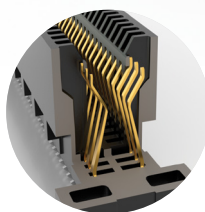
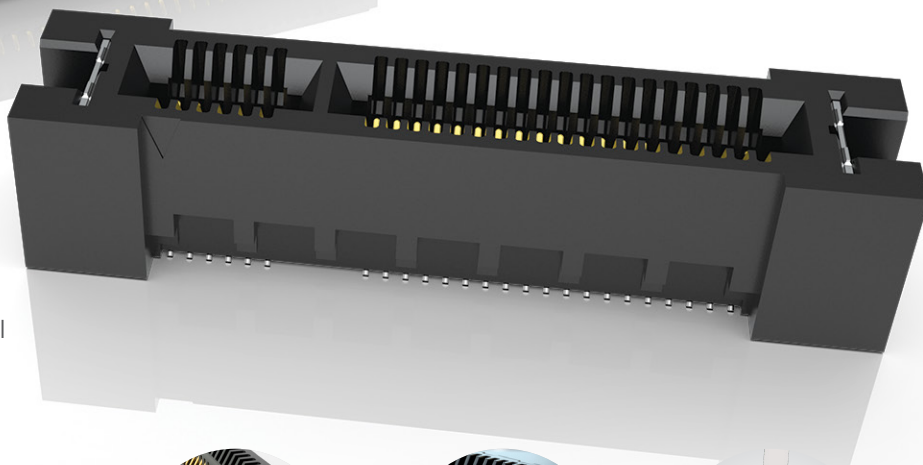


**EDGE
RATE[®]**
CONTACT

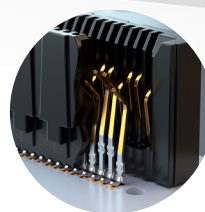
FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

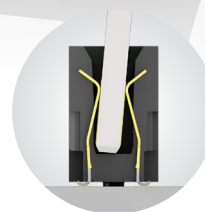
The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked
beam technology
(HTEC8)



Differential pair for
increased speed
(HSEC8-DP)



Custom designs allow
for misalignment in
the X-Y axes (HSEC1)

KEY SPECIFICATIONS

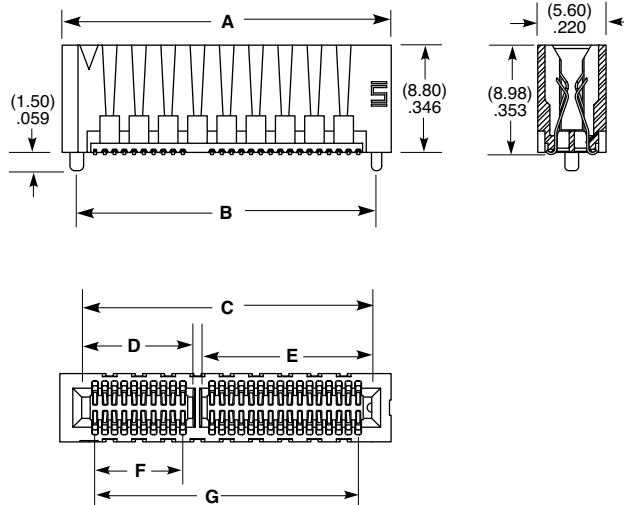
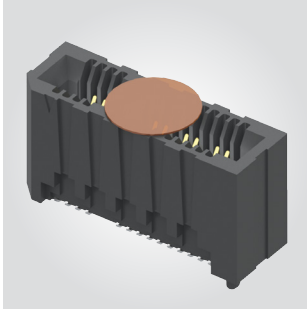
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

0.80 mm (.0315") PITCH • DIFFERENTIAL PAIR EDGE CARD

HSEC8	1	NUMBER OF PAIRS	01	PLATING OPTION	DP	A	OPTION	K	"X"R
		08, 12, 16, 20, 32, 56 (Total Pairs)		-L = 10 μ " (0.25 μ m) Gold on contact area, Matte Tin on tail			Leave blank for no weld tab -WT = Weld Tab	-K = (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad	Leave blank for Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

HSEC8-DP

Card Mates:
(1.60 mm) .062"
thick card



NUMBER OF PAIRS	A	B	C	D	E	F	G
08	(17.40) .685	(15.00) .591	(14.20) .559	(4.34) .171	(9.14) .360	(2.40) .094	(12.00) .472
12	(22.20) .874	(19.80) .780	(19.00) .748	(6.74) .265	(11.54) .454	(4.80) .189	(16.80) .661
16	(27.00) 1.063	(24.60) .969	(23.80) .937	(9.14) .360	(13.94) .549	(7.20) .283	(21.60) .850
20	(31.80) 1.252	(29.40) 1.157	(28.60) 1.126	(11.54) .454	(16.34) .643	(9.60) .378	(26.40) 1.039
32	(46.20) 1.819	(43.80) 1.724	(43.00) 1.693	(18.74) .738	(23.54) .927	(16.80) .661	(40.80) 1.606
56	(75.00) 2.953	(72.60) 2.858	(71.80) 2.827	(33.14) 1.305	(37.94) 1.494	(31.20) 1.228	(69.60) 2.740

Note:
Some sizes, styles and
options are non-standard,
non-returnable.

View complete specifications at: samtec.com?HSEC8-DP